

L Number	Hits	Search Text	DB	Time stamp
-	3990	micro adj spring interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/01 10:29
-	0	micro adj spring adj interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 15:57
-	1	spring adj interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 15:58
-	7	anchor near interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 16:06
-	2	twist\$ near interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 16:07
-	3951	interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 16:09
-	602	deform\$ and interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 16:17
-	1430	spring and interconnect and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 16:19
-	402	spring adj (interconnect or wire or contact) and sensor and (LED or laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 16:23
-	334	spring adj (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/03 19:32
-	448	(spring\$ or deform\$) adj (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 17:10
-	4	257/\$.ccls. and (spring\$ or deform\$) adj (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 17:19
-	29	361/\$.ccls. and (spring\$ or deform\$) adj (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 17:35
-	4	257/\$.ccls. and (spring\$ or deform\$) adj (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 17:36

		4	257/\$.ccls. and (spring\$ or deform\$) near (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/30 17:38
		942	257/\$.ccls. and (interconnect or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/30 17:39
		4	257/\$.ccls. and (spring\$ or deform\$) near (interconnect or lead or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/30 17:40
		93	257/\$.ccls. and (spring\$ or deform\$) same (interconnect or lead or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 13:06
		124	438/\$.ccls. and (spring\$ or deform\$) same (interconnect or lead or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 13:46
		64	438/\$.ccls. and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or lead or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 14:18
		71	257/\$.ccls. and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or lead or wire or contact) and sensor and (LED or laser) and (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 14:42
		27	257/\$.ccls. and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chip or die or circuit or IC) and (glue or elastic\$ or adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 15:07
		1	257/688 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chip or die or circuit or IC) and (glue or elastic\$ or adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 15:16
		6	257/678 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chip or die or circuit or IC) and (glue or elastic\$ or adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 15:23
		6	257/678 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 15:27
		1	257/688 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 15:29
		2	257/689 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/07/31 15:41

		3	257/690 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) same (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB JPO	2001/07/31 15:47
		4	257/\$.ccls. and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 15:55
		149	(curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 15:59
		417	(curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:19
		2	(curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	IBM TDB JPO	2001/07/31 18:35
		462	(interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	JPO	2001/08/03 17:43
		0	257/80 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:23
		0	257/81 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:25
		0	257/82 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:29
		0	257/83 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:31
		0	257/84 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:34
		0	257/91 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:36
		0	257/696 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:39
		2	257/700 and (curve\$ or arch\$ or round\$ or basket-handle\$ or horseshoe\$ or flexible\$) adj (interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/31 20:48

	184595	micro adj spring interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/30 15:56
	3	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:52
	0	sensor and amorphous adj silicon and n+ adj doped and n+ adj phosphorous and n+ adj arsenic and p+ and intrinsic adj amorphous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:30
	0	amorphous adj silicon and n+ adj doped and n+ adj phosphorous and n+ adj arsenic and p+ and intrinsic adj amorphous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:30
	4056	sensor and amorphous adj silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:37
	228	amorphous adj silicon and n+ adj doped	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:39
	2	amorphous adj silicon and n+ adj doped and n+ adj phosphorous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:45
	0	amorphous adj silicon and n+ adj doped and n+ adj phosphorous and arsenic and p+ and intrinsic adj amorphous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:47
	2	n+ adj doped adj amorphous adj silicon and intrinsic adj amorphous adj silicon and p+ adj doped	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:48
	0	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorption and (TFT or thin adj film adj transistor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:55
	0	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorps and (TFT or thin adj film adj transistor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:56
	3	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 21:21
	0	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorps and switch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 20:58
	0	conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorps and (TFT or thin adj film adj transistor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/02 21:00

-	0	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorp\$ adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2001/08/02 21:01
-	0	sensor and conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorp\$ adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2001/08/02 21:02
-	3	conductive adj layer and active adj layer and transpa\$ adj layer and passivation and via and metal and absorp\$	USPAT	2001/08/02 21:23
-	52	conductive adj layer and active and transpa\$ and passivation and via and (metal or wire) and absorp\$	USPAT	2001/08/03 12:39
-	17	(sensor or detector) and conductive adj layer and active and transpa\$ and passivation and via and (metal or wire) and absorp\$	USPAT	2001/08/03 13:25
-	3	(sensor or detector) and conductive adj layer and active and transpa\$ and passivation and via and (metal or wire or plug or stud) and absorp\$ adj (layer or film)	USPAT	2001/08/03 14:06
-	0	(sensor or detector) and conductive adj layer and active and transpa\$ and (passivation same via) and (metal or wire or plug or stud) and absorp\$ adj (layer or film)	USPAT	2001/08/03 13:38
-	8	conductive adj layer and active and transpa\$ and (passivation same via) and (metal or wire or plug or stud) and absorp\$	USPAT	2001/08/03 13:39
-	3	(sensor or detector) and conductive adj layer and active and transpa\$ and passivation and (via or hole or cavity or opening) and (metal or wire or plug or stud) and absorp\$ adj (layer or film)	USPAT	2001/08/03 14:07
-	462	(interconnect or leads or wires or contacts) and sensor and (LED or laser) and (chips or dice or circuits or IC)	JPO	2001/08/03 18:18
-	0	driver adj chip and comparator and converter and register and signal and driver	JPO	2001/08/03 18:21
-	7	comparator and converter and register and signal and driver	JPO	2001/08/03 18:21
-	76	driver adj chip and comparator and converter and register and signal and driver	USPAT	2001/08/03 18:23
-	47	driver adj chip and comparator and converter and register and signal and driver and sensor and (light or LED)	USPAT	2001/08/03 18:24
-	194	sensor and (LED or laser) and driver adj (chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2001/08/03 19:34
-	3	257/\$.ccls. and sensor and (LED or laser) and driver adj (chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2001/08/03 19:35
-	3166	sensor and (LED or laser) and driver adj (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/03 19:56

-	3103	sensor and (LED or light adj source) and driver adj (chip or die or circuit or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2001/08/03 20:42
-	5	5475211.pn. or 6084650.pn. or 4812415.pn. or 5917603.pn. or 5917534.pn.	JPO	2001/08/03 20:53
-	1	03085466.pn.	JPO	2001/08/03 20:59
-	1	03085466.pn.	JPO	2001/08/03 20:59
-	9	5528272.pn. or 5568320.pn. or 5613861.pn. or 5843802.pn. or 5848685.pn. or 5914218.pn. or 5936657.pn. or 5944537.pn. or 5978408.pn.	USPAT	2001/08/03 21:12
-	0	micro adj spring adj (interconnect or wire or layer or film) and sensor and (LED or laser)	USPAT; JPO	2002/01/11 20:53
-	431	spring adj (interconnect or wire or layer or film or contact) and sensor and (LED or laser)	USPAT; JPO	2002/01/11 20:59
-	196	spring adj (interconnect or wire or layer or film or contact) and sensor and (LED or laser) and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 21:47
-	72259	200/\$.ccls. spring adj (interconnect or wire or layer or film or contact) and sensor and (LED or laser) and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 21:48
-	9	200/\$.ccls. and spring adj (interconnect or wire or layer or film or contact) and sensor and (LED or laser) and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 21:52
-	10	200/\$.ccls. and spring adj (interconnect or wire or layer or film or contact) and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 21:54
-	23	200/\$.ccls. and spring adj (interconnect or wire or layer or film or contact) and sensor and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 22:06
-	1	"4320438".PN.	USPAT	2002/01/11 22:00
-	1	"4423401".PN.	USPAT	2002/01/11 22:01
-	1	"4758927".PN.	USPAT	2002/01/11 22:01
-	1	"4758927".PN.	USPAT	2002/01/11 22:02
-	1	"5121298".PN.	USPAT	2002/01/11 22:02
-	1	"5121298".PN.	USPAT	2002/01/11 22:02
-	1	"5152695".PN.	USPAT	2002/01/11 22:02
-	1	"5280139".PN.	USPAT	2002/01/11 22:03
-	1	"3487541".PN.	USPAT	2002/01/11 22:04
-	1	"3689991".PN.	USPAT	2002/01/11 22:05
-	1	"3932689".PN.	USPAT	2002/01/11 22:05
-	1	"4728751".PN.	USPAT	2002/01/11 22:05
-	1	"5121298".PN.	USPAT	2002/01/11 22:05
-	2023	257/\$.ccls. and (interconnect or wire or layer or film or contact) and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 22:07
-	1463	257/\$.ccls. and (interconnect or wire or lead or contact) and portion and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$)	USPAT; JPO	2002/01/11 22:12
-	749	257/\$.ccls. and (interconnect or wire or lead or contact) and portion and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$) and (transparent adj substrate or glass)	USPAT; JPO	2002/01/11 22:14
-	0	257/\$.ccls. and (interconnect or wire or lead or contact) and portion and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$) and (transparent adj substrate or glass) and print adj bar	USPAT; JPO	2002/01/11 22:15

-	0	(257/80 or 257/81 or 257/82 or 257/83 or 257/84) and (interconnect or wire or lead or contact) and portion and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$) and (transparent adj substrate or glass) and print adj bar	USPAT; JPO	2002/01/11 22:16
-	61	(257/80 or 257/81 or 257/82 or 257/83 or 257/84) and (interconnect or wire or lead or contact) and portion and sensor and (LED or laser or (light with device)) and (die or chip or IC or semiconduct\$) and (transparent adj substrate or glass)	USPAT; JPO	2002/01/11 22:17
-	5	"5475211"	USPAT	2002/07/01 10:29
-	6	"5475211"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/01 10:30
-	5	"5475211" and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/01 11:20
-	1128830	sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/01 11:20
-	12	(semiconductor or die or chip or IC) near driver and sensor and lead near frame	USPAT	2003/05/29 16:10
-	26	(semiconductor or die or chip or IC) near driv\$3 and sensor and lead near frame	USPAT	2003/05/29 16:30
-	1575	(semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)	USPAT	2003/05/29 16:40
-	1251	((semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)) and (LED or laser or light or light near (source or emit\$4))	USPAT	2003/05/29 19:44
-	1	"5444599".PN.	USPAT	2003/05/29 17:11
-	1	"5446616".PN.	USPAT	2003/05/29 17:11
-	1	"5613861".PN.	USPAT	2003/05/29 17:11
-	1	"5619071".PN.	USPAT	2003/05/29 17:11
-	1	"5848685".PN.	USPAT	2003/05/29 17:12
-	1	"5914218".PN.	USPAT	2003/05/29 17:12
-	1	"6229684".PN.	USPAT	2003/05/29 17:12
-	1	"3826984".PN.	USPAT	2003/05/29 17:17
-	1	"3842189".PN.	USPAT	2003/05/29 17:18
-	1	"3883949".PN.	USPAT	2003/05/29 17:18
-	1	"4320438".PN.	USPAT	2003/05/29 17:18
-	1	"4423401".PN.	USPAT	2003/05/29 17:18
-	1	"4758927".PN.	USPAT	2003/05/29 17:18
-	1	"5090118".PN.	USPAT	2003/05/29 17:19
-	1	"5121298".PN.	USPAT	2003/05/29 17:19
-	1	"5152695".PN.	USPAT	2003/05/29 17:19
-	1	"5152695".PN.	USPAT	2003/05/29 17:20
-	1	"5214563".PN.	USPAT	2003/05/29 17:20
-	1	"5280139".PN.	USPAT	2003/05/29 17:20
-	1	"5334031".PN.	USPAT	2003/05/29 17:20
-	1	"5665648".PN.	USPAT	2003/05/29 17:21
-	1	"5801441".PN.	USPAT	2003/05/29 17:22
-	1	"5860818".PN.	USPAT	2003/05/29 17:22
-	1	"3826984".PN.	USPAT	2003/05/29 17:27
-	1	"5665648".PN.	USPAT	2003/05/29 17:27
-	1	"2562685".PN.	USPAT	2003/05/29 17:33
-	1	"3356369".PN.	USPAT	2003/05/29 17:33
-	1	"4320438".PN.	USPAT	2003/05/29 17:33
-	1	"4423401".PN.	USPAT	2003/05/29 17:33
-	1	"4758927".PN.	USPAT	2003/05/29 17:33
-	1	"5121298".PN.	USPAT	2003/05/29 17:33
-	1	"5152695".PN.	USPAT	2003/05/29 17:33
-	1	"4320438".PN.	USPAT	2003/05/29 17:34

-		1	"4423401".PN.	USPAT	2003/05/29 17:34
-		1	"4758927".PN.	USPAT	2003/05/29 17:34
-		1	"5121298".PN.	USPAT	2003/05/29 17:34
-		1	"5152695".PN.	USPAT	2003/05/29 17:35
-		1	"5280139".PN.	USPAT	2003/05/29 17:35
-		95	((semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)) and (LED or laser or light or light near (source or emit\$4)) and array near LEDs	USPAT	2003/05/29 22:07
-		0	((semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)) and (LED or laser or light or light near (source or emit\$4)) and array near LEDs and printbar with sensor	USPAT	2003/05/29 22:08
-		0	((semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)) and (LED or laser or light or light near (source or emit\$4)) and array near LEDs and printbar with LED	USPAT	2003/05/29 22:22
-		1251	((semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)) and (LED or laser or light or light near (source or emit\$4))	USPAT	2003/05/29 22:22
-		0	((semiconductor or die or chip or IC) near driv\$3 and sensor and (lead or wire)) and (LED or laser or light or light near (source or emit\$4))) and printbar	USPAT	2003/05/29 22:22
-		0	((semiconductor or die or chip or IC) and sensor and (LED or laser or light or light near (source or emit\$4)) and array near LEDs and printbar with LED	USPAT	2003/05/29 22:24
-		3	(semiconductor or die or chip or IC) and array near LEDs and printbar with LED	USPAT	2003/05/29 23:06
-		2	5859658.pn. or 5142381.pn.	USPAT	2003/05/29 23:06
-	1278		(semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)	USPAT	2004/02/05 14:08
-		161	((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) and sensor with ("on" or over or above) with (base or substrate or board)	USPAT	2004/02/05 15:26
-		1	"4751505".PN.	USPAT	2004/02/05 14:15
-		1	"4799055".PN.	USPAT	2004/02/05 14:15
-		1	"4804949".PN.	USPAT	2004/02/05 14:15
-		1	"5086197".PN.	USPAT	2004/02/05 14:15
-		1	"5517211".PN.	USPAT	2004/02/05 14:16
-		0	((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) and sensor with ("onto") with (base or substrate or board)	USPAT	2004/02/05 15:27
-		277	((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) and sensor with direct\$3 with (light or "laser beam")	USPAT	2004/02/05 16:19
-		135	((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) and sensor with "pass" with (light or "laser beam")	USPAT	2004/02/05 16:28

	841	((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) not (((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) and sensor with ("on" or over or above) with (base or substrate or board)) or (((semiconductor or die or chip or integrated or IC) and sensor with (wir\$3 or lead) same (laser or LED or light near source)) and sensor with "pass" with (light or "laser beam")))	USPAT	2004/02/05 16:29
	1	"3842189".PN.	USPAT	2004/02/05 17:11
	1	"5399232".PN.	USPAT	2004/02/05 17:11
	1	"5465611".PN.	USPAT	2004/02/05 17:11
	1	"5613861".PN.	USPAT	2004/02/05 17:11
	1	"5831181".PN.	USPAT	2004/02/05 17:16
	1	"5939623".PN.	USPAT	2004/02/05 17:16
	1	"5960147".PN.	USPAT	2004/02/05 17:17
	1	"6011261".PN.	USPAT	2004/02/05 17:17
	1	"6441359".PN.	USPAT	2004/02/05 17:17
	1	"6528785".PN.	USPAT	2004/02/05 17:17
	47502	((semiconductor or die or chip or integrated or IC) and (light or optical) near (sensor or detector) with "connected by" "with (wir\$3 or lead) with (laser or LED or diode or ccd or light near (source or bulb))")	USPAT	2004/02/06 21:06
	0	((semiconductor or die or chip or integrated or IC) and (light or optical) near (sensor or detector) with "connected by" with (wir\$3 or lead) with (laser or LED or diode or ccd or light near (source or bulb)))	USPAT	2004/02/06 21:06
	27	((semiconductor or die or chip or integrated or IC) and (light or optical) near (sensor or detector) with connected with (wir\$3 or lead) with (laser or LED or diode or ccd or light near (source or bulb)))	USPAT	2004/02/06 21:15
	831	((semiconductor or die or chip or integrated or IC) and (light or optical) near (sensor or detector) with connect\$3 with (laser or LED or diode or ccd or light near (source or bulb)))	USPAT	2004/02/06 23:12
	9672	((semiconductor or die or chip or integrated or IC) and (light or optical) near (sensor or detector) with (laser or LED or diode or ccd or light near (source or bulb)))	USPAT	2004/02/06 23:13
	143	((semiconductor or die or chip or integrated or IC) and (light or optical) near (sensor or detector) with (laser or LED or diode or ccd or light near (source or bulb))) and (direct or directly) with (light or beam) with pass\$3 near through with (sens\$3 or detector)	USPAT	2004/02/06 23:14